Session Program

20–24 Sept 2010

TWEPP 2010 Topical Workshop on Electronics for Particle Physics

Packaging and Interconnects

Aachen, Germany
RWTH Aachen University Templergraben 55 52056 Aachen

Wednesday 22 September

15:05

Packaging and Interconnects: Parallel Session A4

Session | **Location:** Aula | **Convener:** Mr Ray Yarema

15:05–15:30 **Low-cost bump bonding activities at CERN**

Speaker
Mr Sami Vaehaenen

15:30–15:55

Design and Performance of Serial Powered Single-Sided Modules within an Integrated Stave Assembly for the ATLAS Tracker Barrel Upgrade

Speaker
Mr Ashley Greenall

15:55–16:20

SLID-ICV interconnection technology for the ATLAS pixel upgrade at SLHC

Speaker
Michael Beimforde

16:20